Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 5500-24G-SFP HI Switch w/2 Intf Slt(JG543A)
HP 5500-24G-SFP HI TAA Swch w/2Slt(JG681A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Tweezers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws for mounting angle 1, and then remove the mounting angle 1 from the rack.
2. Remove all of the labels.
3. Unscrew the screws on filler panel 2 and 3, and then remove them.
4. Unscrew the screws on top cover 4, and then remove it.
5. Unscrew the screws on PCB-assembly 5, and then remove the assembly.
6. Remove the light pipes 6,7,8,9 on the PCB-assembly 5.
7. Unscrew the screws on fans 10 and 11, remove them from chassis assembly 13.
8. Remove the front panel assembly 12 from chassis assembly 13.
9. Remove shielding fingers 3.1 from filler panel 3.
10. Unscrew the screws on part 5.1, remove it from PCB-assembly 5.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

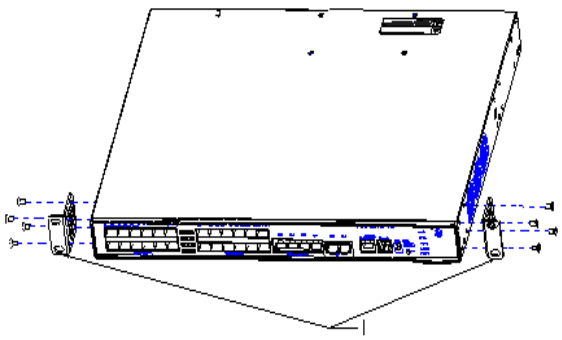

Figure 1 Remove mounting angle

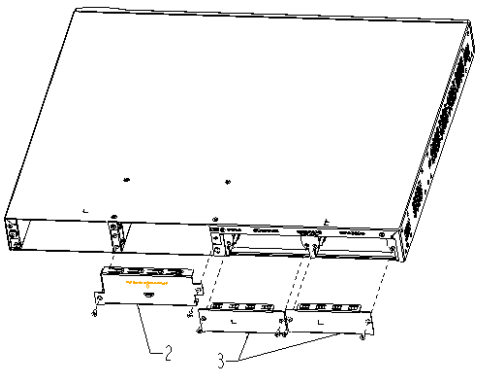

Figure 2 Rear of HP 5500-24G-SFP HI Switch

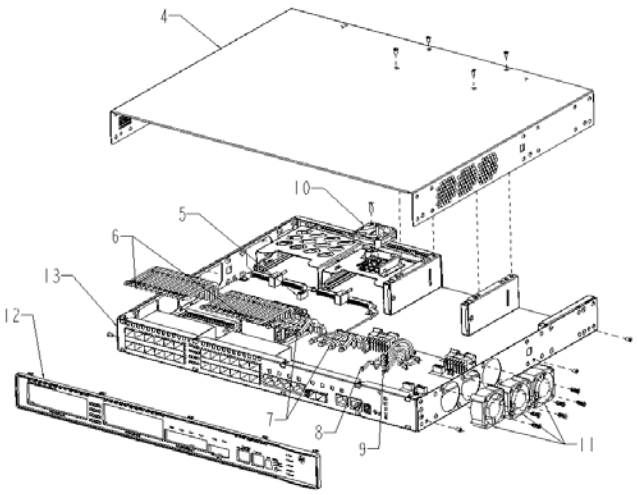

Figure 3 Treatments to the product

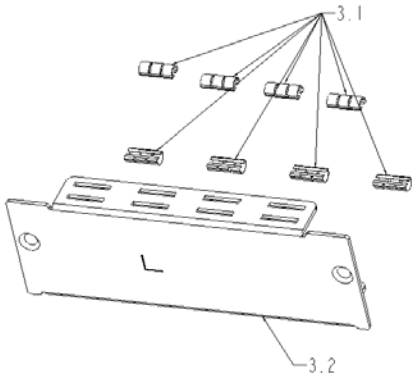

Figure 4 Treatments to the filler panel 3

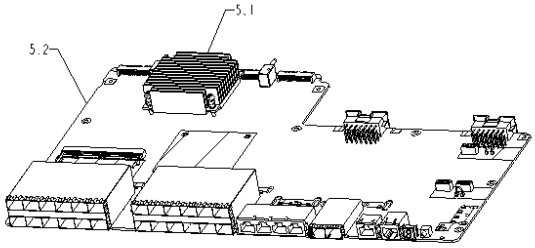

Figure 5 Treatments to PCB-assembly

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	76	1.6%		Fe recycling
2		Fe	50	1.1%		Fe recycling
3	3.2	Fe	80	1.7%		Fe recycling
4		Fe	1460	30.7%		Fe recycling
5	5.1	Al	100	2.1%		Al recycling

	5.2	Complex PCB	1010	21.3%	The surface of PCB is greater than 10 square centimeters;	
6		PC	33	0.7%		Pla recycling
10		PC	20	0.4%		
11		PC	90	1.9%		
12		PC+ABS	50	1.1%		Pla recycling
13		Fe	1860	39.2%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2012.11.20	V0	Wang Zitao	Initial version
2013.04.10	V1	Liu Baoquan	Add the module JG681A